## **MN74HC08/MN74HC08S**

## Quad 2-Input AND Gates

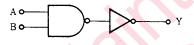
#### ■ Outline

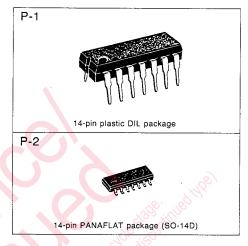
The MN74HC08/MN74HC08S is a 2-input positive AND gate having four built-in circuits in one chip.

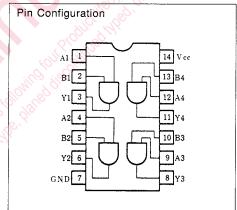
Owing to the silicon gate CMOS process, this AND gate has realized low power consumpiton and high noise immunity equivalent to those of a standard CMOS and the operation speed as high as of an LS TTL. The buffer added to the gate output improves the input/output transfer characteristic and minimizes the propagation delay time fluctuation caused by the load capacity increase. The MN74HC08/MN74HC08S can directly drive ten LS TTL inputs.

To protect the input and output against electrostatic breakdown, a resistor and a diode are used for the  $V_{\text{CC}}$  and the GND. The pin configuration and the function are the same as those of the standard 54LS/74LS logic family.

#### ■ Logic Diagram (1 Gate)







■ Absolute Maximum Ratings

	Item		Symbol	Rating	Unit	
Supply voltage			V <sub>cc</sub>	-0.5~+7.0	V	
Input output voltage		V <sub>i</sub> , V <sub>o</sub>	-0.5~V <sub>cc</sub> +0.5	V		
Input protective diode current			$I_{ik}$	±20	mA	
Output parasitic diode current			I <sub>ok</sub>	±20	mA	
Output current			Io	±25	mA	
Supply current			I <sub>CC</sub> , I <sub>GND</sub>	±50	mA	
Storage temperature			$T_{\rm stg}$	-65~+150	°C	
Power dissipation	MN74HC08	Ta=-40~+60°C	$P_{D}$	400	mW	
		$Ta = +60 \sim +85^{\circ}C$	I FD	Decrease to 200mW at the rate of 8mW/°C	¬ inw	
	MN74HC08S	Ta=-40~+60°C	ъ	275	mW	
	WIN/4HC085	$Ta = +60 \sim +85^{\circ}C$	$P_{D}$	Decrease to 200mW at the rate of 3.8mW/°C		

#### ■ Recommended Operating Conditions

Item	Symbol	V <sub>cc</sub> (V)	Rating	Unit
Operating power supply voltage	V <sub>cc</sub>		1.4~6.0	. V
Input output voltage	V <sub>I</sub> , V <sub>O</sub>		0~Vcc	V
Operating temperature	T <sub>A</sub>		<b>−40~+85</b>	°C
		2.0	0~1000	ns
Input rise, fall time	t <sub>r</sub> , t <sub>f</sub>	4.5	0~500	ns
		6.0	0~400	ns

#### ■ DC Characteristics (GND=0V)

	Symbol	V <sub>cc</sub> (V)	Test Condition			Temperature					
Item			Vı	T		Ta=25°C			Ta=-40~+85°C		Unit
				I <sub>O</sub>	Unit	min.	typ.	max.	min.	max.	
		2.0				1.5			1.5		
Input voltage high level	V <sub>IH</sub>	4.5				3.15			3.15		V
		6.0				4.2			4.2		
-		2.0						0.3		0.3	
Input voltage low level	$V_{IL}$	4.5						0.9		0.9	V
		6.0	l ,			. (		1.2	we.	1.2	
		2.0		-20.0	μΑ	1.9	2.0		1.9		
		4.5		-20.0	μΑ	4.4	4.5		4.4		
Output voltage high level	V <sub>OH</sub>	6.0	$V_{IL}$	-20.0	$\mu$ A	5.9	6.0		5.9		V
		4.5		-4.0	mA	3.92	Ď <sub>1.1</sub> ,	11000	3.84		
		6.0		-5.2	mA	5.48	0,000		5.34		
		2.0		20.0	μA	3	0.0	0.1		0.1	
		4.5	V <sub>IH</sub>	20.0	$\mu$ A		0.0	0.1		0.1	
Output voltage low level	V <sub>OL</sub>	6.0	or	20.0	μΑ	Jilles E	0.0	0.1		0.1	V
		4.5	V <sub>IL</sub>	4.0	mA	09, "		0.26		0.33	
		6.0		5.2	mA	9/311,		0.26		0.33	
Input leakage current	$I_{\rm I}$	6.0	$V_{\rm I} = V_{\rm CO}$	or GNI	200° CC	,		±0.1		±1.0	μΑ
Static supply current	Icc	6.0	$V_I = V_{CC}$	or GNI	$I_0 = 0$			2.0		20.0	μΑ

## ■ AC Characteristics (GND=0V, Input transition time≤6ns, C<sub>L</sub>=50pF)

	Symbol	V <sub>CC</sub> (V) Test Condition							
Item			Ta=25°C			Ta=-40~+85°C		Unit	
				min.	typ.	max.	min.	max.	
		2.0	S		25	75		95	
Output rise time	t <sub>TLH</sub>	4.5			8	15		19	ns
i .		6.0			7	13		16	
	24	2.0			20	75		95	
Output fall time	tTHL	4.5			7	15		19	ns
	10/0.	6.0			6	13		16	
		2.0			25	75		95	
Propagation time (L→H)	t <sub>PLH</sub>	4.5			8	15		19	ns
		6.0			7	13		16	
	) t <sub>PHL</sub>	2.0			25	75		95	
Propagation time $(H\rightarrow L)$		4.5			8	15		19	ns
		6.0			7	13		16	

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